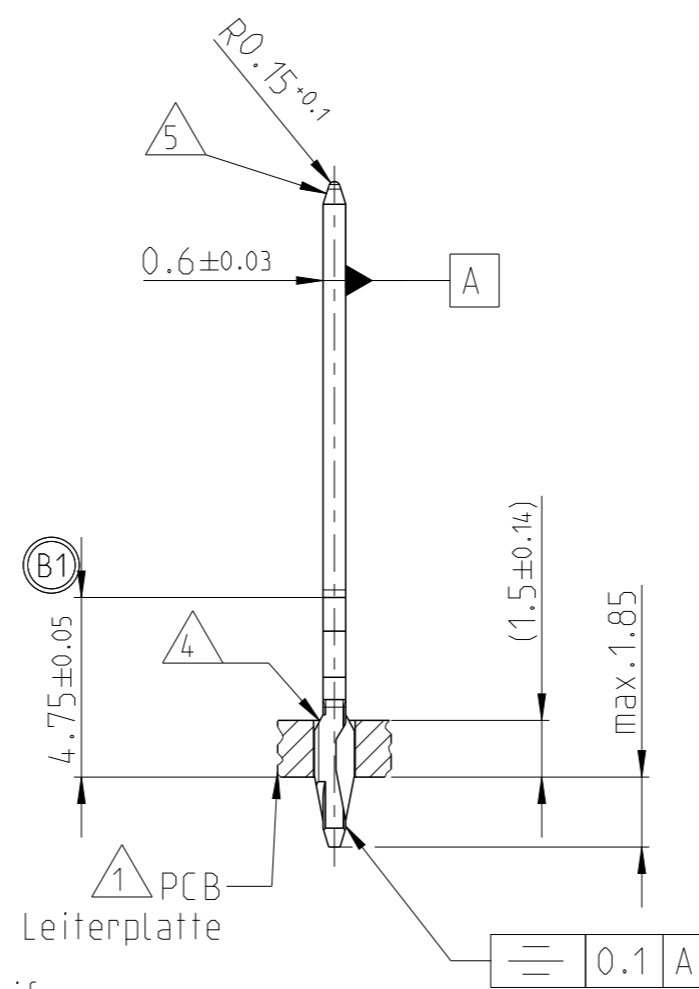
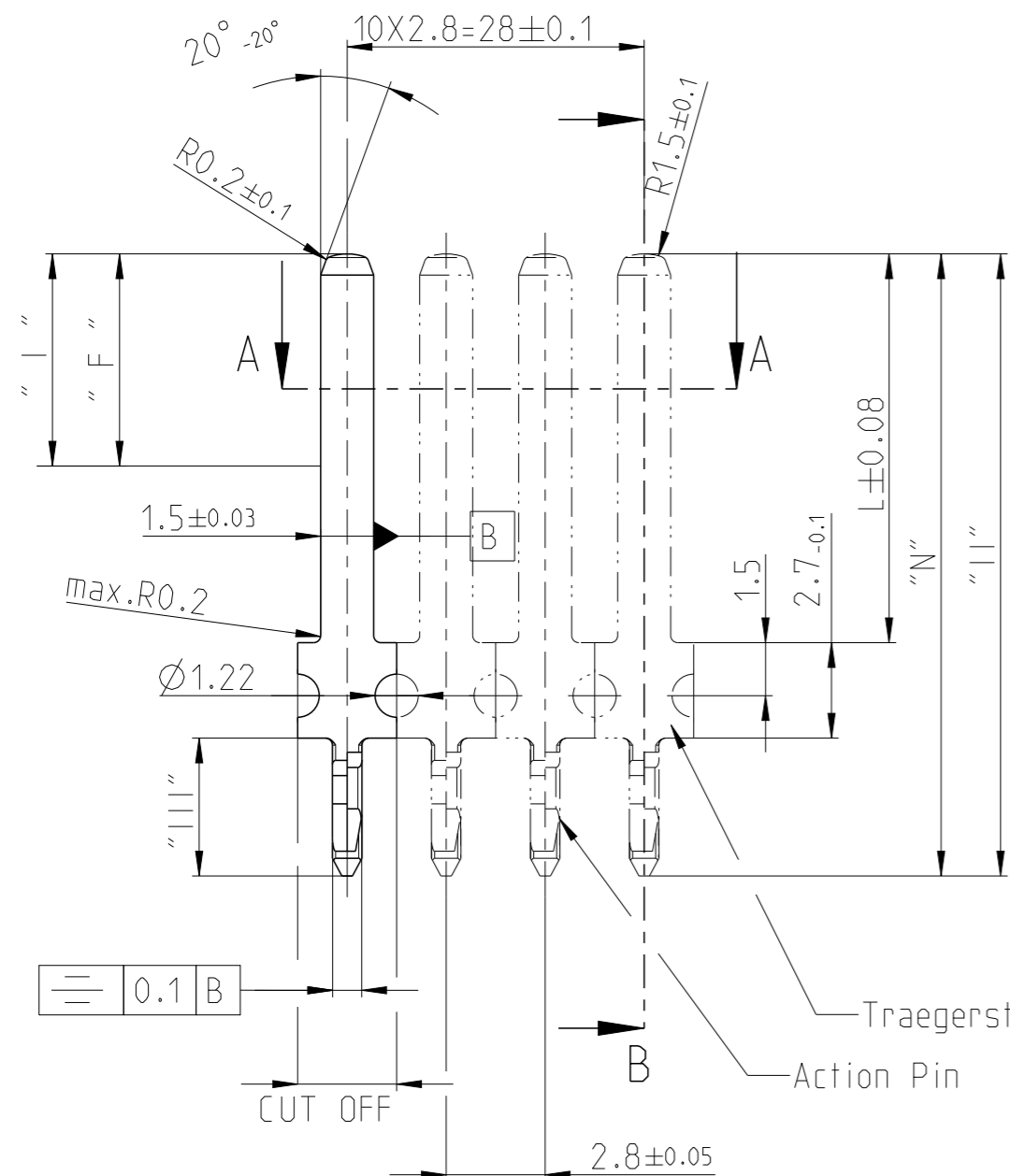
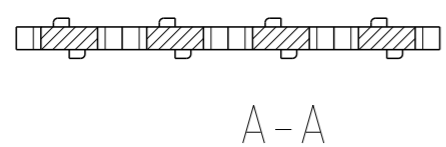


P	LTR	DESCRIPTION	DATE	DWN	APVD
	B	NEW DRAWING	10JUN2015	KK	DD
	B1	DRW UPDATE, POSITION PCB CORRECTED	07DEC2015	ST	SR



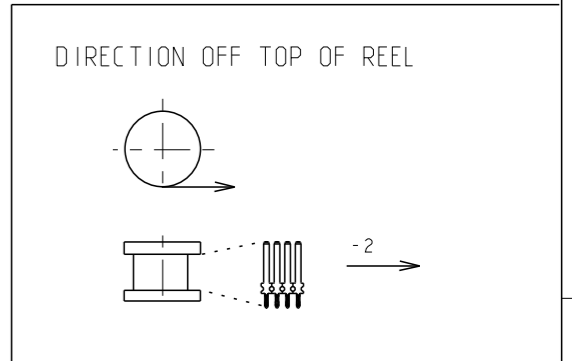
- Bemerkungen
NOTES
- 1 Verwendung fuer Leiterplattendicke 1.5 ±0.14mm(FR4)
USED ON PCB-THICKNESS...
 - 2. Verarbeitungswerkzeug: X-Y-Einsetzmaschine
APPLICATION TOOL: X-Y-INSERTIONMACHINE
 - 3. Loetbarkeit nach DIN 40 046
SOLDERABILITY ACCORDING TO
 - 4 Einpresszone fuer 1.5 mm Leiterplatte
Anforderungen an Leiterplatten-Loch
PRESS-IN AREA FOR PCB
REQUIREMENTS ON PCB-HOLE
- Plattiertes Loch:
PLATED HOLE:...
- gebohrtes Loch: 1.15±0.025mm
DRILLED HOLE :
 - Cu - Dicke : 25 µm bis 75 µm
...THICKNESS :
 - Sn-Dicke : 4 µm bis 15 µm
...THICKNESS :
 - Fertiges Loch : 0.94mm bis 1.09mm
FINISHED HOLE :
- 5 Kein Grat oder scharfe Kanten zulaessig
NO BURRS OR SHARP EDGES PERMITTED
 - 6 Splice frei
SPLICE FREE
- Massgebend ist der deutsche Text.
ONLY THE GERMAN LANGUAGE VERSION SHALL BE BINDING.



Zone "I" : Schichtdicke 1.0µm bis 3.0µm Sn
AREA "I" : COAT THICKNESSUNTIL...

Zone "II" : Schichtdicke 1.3µm bis 2.2µm Ni
AREA "II" : COAT THICKNESSUNTIL...

Zone "III" : Schichtdicke 0.8µm bis 1.8µm Sn
AREA "III" : COAT THICKNESSUNTIL...



1394353-2	B	CuNiSi F59	Sn	8	10.3	16.9
PART NO Bestell-Nr.	REV	MATERIAL	SURFACE Oberflaeche	"F"	"L"	"N"

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS:	TOLERANCES UNLESS OTHERWISE SPECIFIED:
mm	
	Ø PLC ±0.1
	1 PLC ±
	2 PLC ±
	3 PLC ±
	4 PLC ±
	ANGLES ±1°
MATERIAL	FINISH
-	-
-	-

DWN	K.Kappes	10JUN2015
CHK	S.Reichel	10JUN2015
APVD	D.Duenkel	10JUN2015
PRODUCT SPEC	-	-
APPLICATION SPEC	-	-
WEIGHT	-	-

STE TE Connectivity

NAME
1.5x0.6 Tab, ACTION PIN FOR 1mm HOLE
1.5x0.6 Tab, ACTION PIN fuer 1mm Loch
FREE STANDING/freistehend

SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
A3	-	C-1394353	-

Customer Drawing SCALE 5:1 SHEET 1 OF 1 REV B1